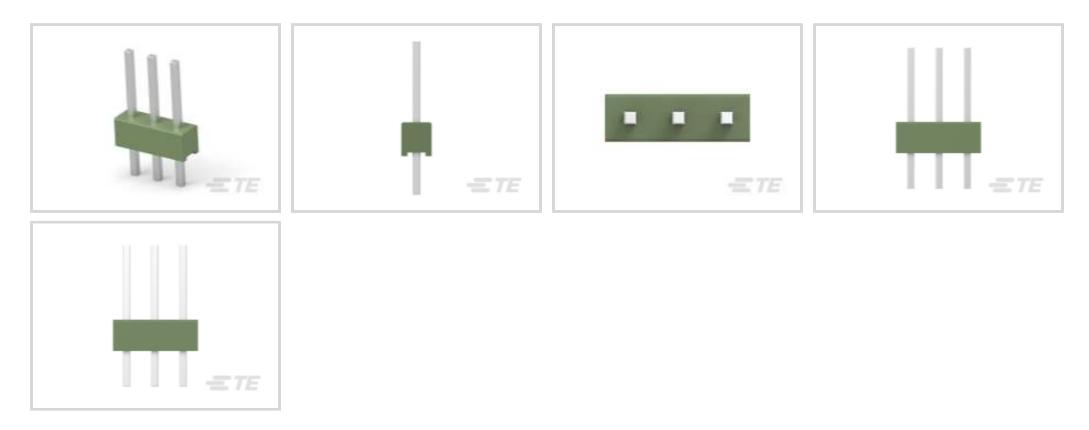
# 826936-3 - ACTIVE

### AMPMODU | AMPMODU Headers

TE Internal #: 826936-3 PCB Mount Header, Vertical, Board-to-Board, 3 Position, 2.54 mm [. 1 in] Centerline, Breakaway, Tin, Through Hole - Solder, Signal, AMPMODU Headers

#### View on TE.com >

#### Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 3

Number of Rows: 1

### Features



### **Product Type Features**

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Breakaway
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Connector Contact Load Condition	Fully Loaded
	Vertical
PCB Mount Orientation	vertical
Number of Positions	3
Number of Positions	3
Number of Positions Number of Rows	3
Number of Positions Number of Rows Board-to-Board Configuration	3

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## **Body Features**

Green
.64 mm[.025 in]
2 µm
Square
Nickel
Tin
Phosphor Bronze
Tin
3 μm[118.11 μin]
Pin
5 A
.64 mm[.025 in]
3.2 mm[.126 in]
Through Hole - Solder

## Mechanical Attachment

Circuit Application	Signal
Operation/Application	
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
Housing Temperature Rating	Standard
Usage Conditions	
PCB Thickness (Recommended)	1.57 mm[.062 in]
Dimensions	
Housing Material	PBT
Centerline (Pitch)	2.54 mm[.1 in]
Housing Features	
Connector Mounting Type	Board Mount
PCB Mount Alignment	Without
PCB Mount Retention	Without
Mating Alignment	Without

**C** For support call+1 800 522 6752

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Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	1500
Packaging Type	Carton
<b>Product Compliance</b> For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2023 (233) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 265°C

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

## **Compatible Parts**

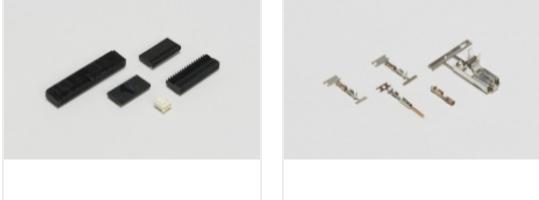
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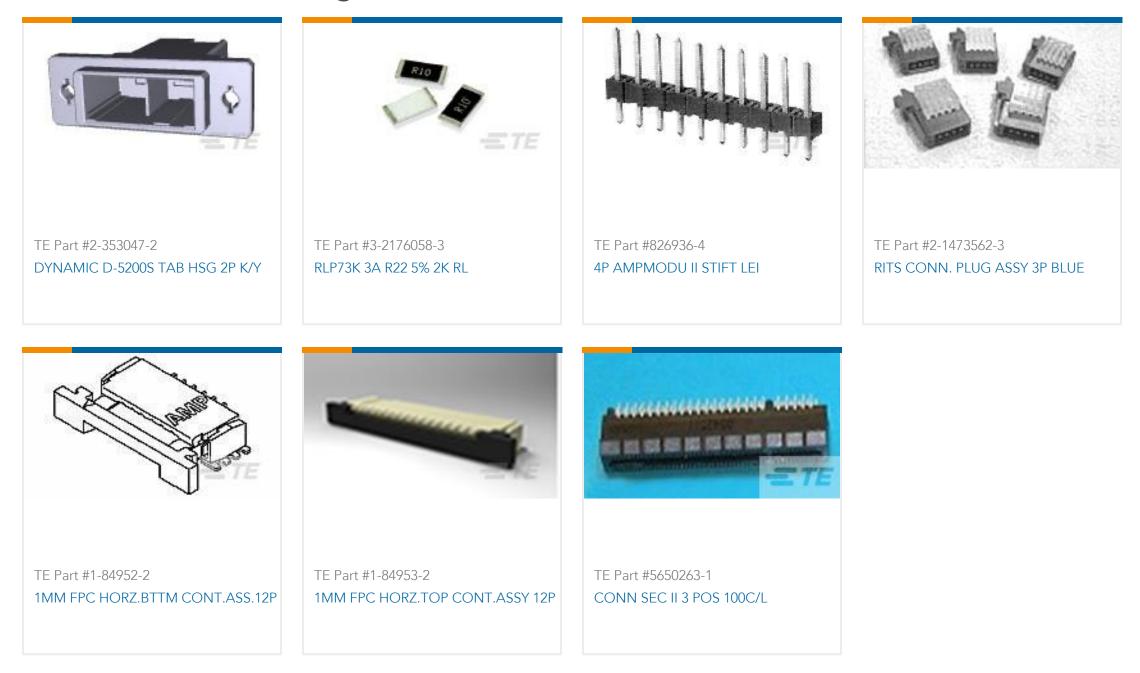
# Also in the Series AMPMODU Headers





Wire-to-Board Connector Assemblies	Wire-to-Board Connector Contacts(65)
& Housings(5)	

# Customers Also Bought



PCB Mount Header, Vertical, Board-to-Board, 3 Position, 2.54 mm [.1 in] Centerline, Breakaway, Tin, Through Hole - Solder, Signal, AMPMODU Headers



## Documents

Product Drawings 3P AMPMODU II STIFT LEI

English

### **CAD** Files

3D PDF

3D

Customer View Model

ENG\_CVM\_CVM\_826936-3\_J.2d\_dxf.zip

English

Customer View Model

ENG\_CVM\_CVM\_826936-3\_J.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_CVM\_826936-3\_J.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

### **Product Environmental Compliance**

**Product Compliance** 

English

**Product Compliance** 

English

Agency Approvals UL Report

English